

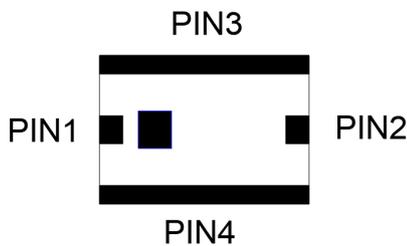
Features

- Multilayer monolithic construction yields high reliability
- Low insertion loss and small size SMD chip design
- Can simplify your complex tuning and circuit design
- LTCC process

Specifications

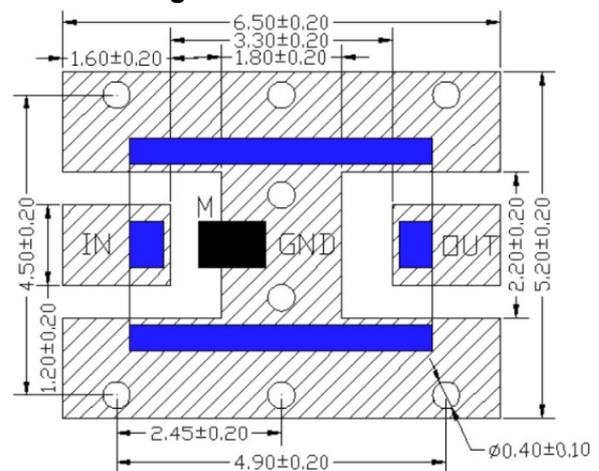
NO.	Parameter	Frequency (MHz)	SPEC	
			Min.	Max.
1	Insertion Loss (dB)	1350~1650		3.0
2	Ripple (dB)	1350~1650		0.5
3	Attenuation (dB)	DC~650	50	
		2350~3300	50	
4	VSWR	1350~1650		1.5
5	In/Output Impedance (Ω)		50	
6	Permissible Input Power (W)		5Max.	
7	Operation Temperature Range		-40°C ~ +85°C	

Construction



PIN	Connection
1	Input Port
2	Output Port
3	GND
4	GND

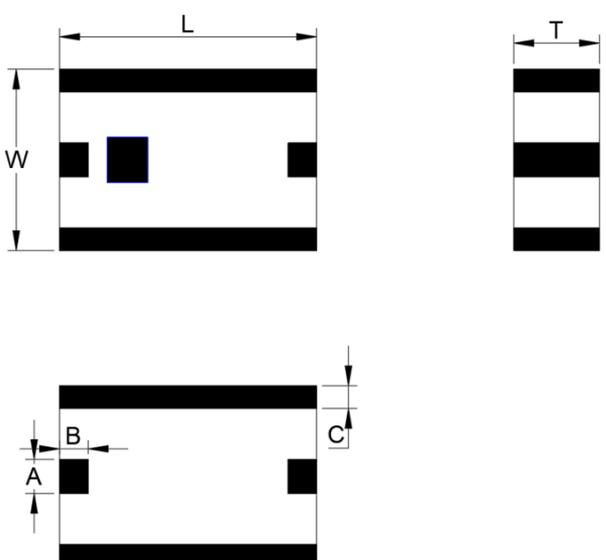
Mounting Considerations



Unit: mm

Line width to be designed to match 50 Ω characteristic impedance, depending on PCB material and thickness

Dimensions

Figure	Symbol	Dimension (mm)
	L	4.50±0.20
	W	3.20±0.20
	T	1.50±0.20
	A	0.60±0.10
	B	0.50±0.10
	C	0.40±0.10

Typical Electrical Characteristics (T=25°C)

